

February 2001 Revised February 2001

FSTD3306

2-Bit Low Power Bus Switch with Level Shifting

General Description

The FSTD3306 is a 2-bit ultra high-speed CMOS FET bus switch with enhanced level shifting circuitry and with TTL-compatible active LOW control inputs. The low on resistance of the switch allows inputs to be connected to outputs with minimal propagation delay and without generating additional ground bounce noise. The device is organized as a 2-bit switch with independent bus enable (\overline{BE}) controls. When \overline{BE} is LOW, the switch is ON and Port A is connected to Port B. When \overline{BE} is HIGH, the switch is OPEN and a high-impedance state exists between the two ports. Reduced voltage drive to the gate of the FET switch permits nominal level shifting of 5V to 3V through the switch. Control inputs tolerate voltages up to 5.5V independent of $V_{\rm CC}$.

Features

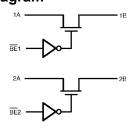
- \blacksquare Typical 3Ω switch resistance at 5.0V V_{CC}, V_{IN} = 0V
- Level shift facilitates 5V to 3.3V interfacing
- Minimal propagation delay through the switch
- Power down high impedance input/output
- Zero bounce in flow through mode
- TTL compatible active LOW control inputs
- Control inputs are overvoltage tolerant

Ordering Code:

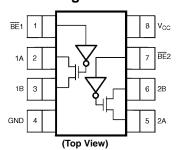
Order Number	Package Number	Package Description
FSTD3306MTC	MTC08	8-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Diagram



Connection Diagram



Pin Descriptions

Pin Name	Description
A	Bus A Switch I/O
В	Bus B Switch I/O
BE	Bus Enable Input

Function Table

Bus Enable Input (BE)	Function			
L	B Connected to A			
Н	Disconnected			

H = HIGH Logic Level L = LOW Logic Level

Absolute Maximum Ratings(Note 1)

Storage Temperature Range (T_{STG}) $-65^{\circ}C$ to $+150^{\circ}C$ Junction Temperature under Bias (T_{J}) $+150^{\circ}C$

under Bias (T_J) Junction Lead Temperature (T_L)

 $\label{eq:conds} \begin{tabular}{ll} (Soldering, 10 Seconds) & +260 \ensuremath{^{\circ}C} \\ Power Dissipation (P_D) @ +85 \ensuremath{^{\circ}C} \\ \ensuremath{\mbox{250}} mW \\ \ensuremath{\mbox{250}} mW \\ \ensuremath{\mbox{250}} \ensuremath{\mbox{250}} mW \\ \ensuremath{\mbox{250}} \ensuremath{\mbox$

Recommended Operating Conditions (Note 3)

Control Input 0 ns/V to 5 ns

Switch I/O 0 ns/V to DC Thermal Resistance (θ_{JA}) 250°C/W

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Note 3: Unused logic inputs must be held HIGH or LOW. They may not float

DC Electrical Characteristics

Symbol	ool Parameter	V _{CC}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			Units	Conditions
Symbol		(V)	Min	Тур	Max	Units	Conditions
V _{IK}	Clamp Diode Voltage	4.5			-1.2	V	I _{IN} = -18 mA
V _{IH}	HIGH Level Input Voltage	4.5-5.5	2.0			V	
V _{IL}	LOW Level Input Voltage	4.5-5.5			8.0	V	
V _{OH}	HIGH Level Output Voltage	4.5–5.5		see Figure 3		V	$V_{IN} = V_{CC}$
I _{IN}	Input Leakage Current	5.5			±1.0	μΑ	0 ≤ V _{IN} ≤ 5.5V
l _{OFF}	Power OFF Leakage Current	5.5			±1.0	μΑ	$0 \le A, B \le V_{CC}$
R _{ON}	Switch On Resistance	4.5		3	7		$V_{IN} = 0V, I_{IN} = 64 \text{ mA}$
	(Note 4)	4.5		3	7	Ω	$V_{IN} = 0V$, $I_{IN} = 30 \text{ mA}$
		4.5		15	50	1	$V_{IN} = 2.4V$, $I_{IN} = 15 \text{ mA}$
Icc	Quiescent Supply Current	5.5					$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$
				1.1	1.5	mA	$BE_1 = BE_2 = GND$
					10	μΑ	$BE_1 = BE_2 = V_{CC}$
ΔI _{CC}	Increase in I _{CC} per Input	5.5		1	2.5	mA	$V_{IN} = 3.4V$, $I_O = 0$, one Control
	(Note 5)	3.5		'			Input Only, Other BE = V _{CC}

Note 4: Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

Note 5: Per TTL driven input ($V_{IN} = 3.4V$, control input only). A and B pins do not contribute to I_{CC} .

AC Electrical Characteristics

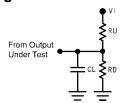
			T _A =	-40°C to +8	35°C,			
Symbol	Parameter	V _{cc}	$\textbf{C}_{\textbf{L}} = \textbf{50}~\text{pF, RU} = \textbf{RD} = \textbf{500}\Omega$			Units	Conditions	Figure Number
		(V)	Min	Тур	Max			
t _{PHL} ,	Prop Delay Bus to Bus	4.5–5.5			0.25	ns	V _I = OPEN	Figures
t _{PLH}	(Note 6)							1, 2
t _{PZL} ,	Output Enable Time	4.5-5.5	1.0	3.5	5.8	ns	V _I = 7V for t _{PZL}	Figures
t _{PZH}							$V_I = 0V$ for t_{PZH}	1, 2
t _{PLZ} ,	Output Disable Time	4.5–5.5	0.8	3.5	4.8	ns	$V_I = 7V$ for t_{PLZ}	Figures
t _{PHZ}							$V_I = 0V$ for t_{PHZ}	1, 2

Note 6: This parameter is guaranteed. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance). The specified limit is calculated on this basis.

Capacitance

Symbol	Parameter	Тур	Max	Units	Conditions
C _{IN}	Control Pin Input Capacitance	2.5		pF	V _{CC} = 0V
C _{I/O} (OFF)	Port OFF Capacitance	6		pF	$V_{CC} = 5.0V = \overline{BE}$
C _{I/O} (ON)	Port ON Capacitance	12		pF	$V_{CC} = 5.0V, \overline{BE} = 0V$

AC Loading and Waveforms



Input driven by 50Ω source terminated in 50Ω C_L includes load and stray capacitance Input PRR = 1.0 MHz; $t_W=500$ ns

FIGURE 1. AC Test Circuit

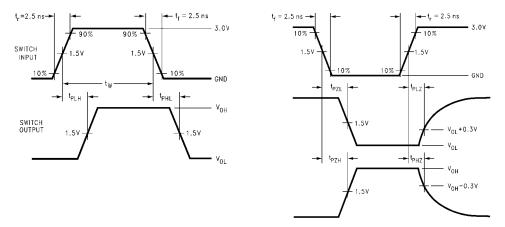
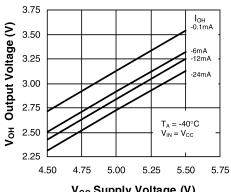
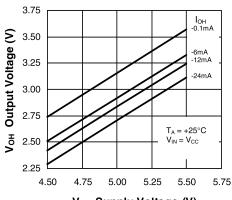


FIGURE 2. AC Waveforms

DC Characteristics



V_{CC} Supply Voltage (V)



V_{CC} Supply Voltage (V)

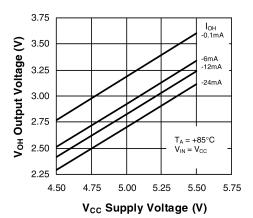


FIGURE 3. Typical High Level Output Voltage vs. Supply Voltage

Physical Dimensions inches (millimeters) unless otherwise noted 7.72 TYP 6.4 4.16 TYP -B-3.2 0.2 C B A 0.65 TYP PIN #1 IDENT. LAND PATTERN RECOMMENDATION SEE DETAIL A △ 0.1 C - 0.90 +0.15 -0.10 -C--0.10±0.05 0.65 TYP ⊕ 0.13 M A B S C S 12° TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS B0.09 MIN GAGE PLANE 0.25 A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND 0.6 ± 0.1 SEATING PLANE D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. 1.00 MTC08RevA1 DETAIL A

8-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC08

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